

# Nagarajan Palavesam

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/6723052/publications.pdf>

Version: 2024-02-01

8  
papers

95  
citations

2682572

2  
h-index

2917675

2  
g-index

8  
all docs

8  
docs citations

8  
times ranked

143  
citing authors

#	ARTICLE	IF	CITATIONS
1	Advanced integration technology for fabricating high-speed electro-optical sub-assembly. , 2021, , .		0
2	Influence of Flexibility of the Interconnects on the Dynamic Bending Reliability of Flexible Hybrid Electronics. Electronics (Switzerland), 2020, 9, 238.	3.1	9
3	Roll-to-roll processing of film substrates for hybrid integrated flexible electronics. Flexible and Printed Electronics, 2018, 3, 014002.	2.7	68
4	Low Profile Open MEMS and ASIC Packages manufactured by Flexible Hybrid Integration in a Roll-to-Roll compatible process. , 2018, , .		4
5	Electrical behaviour of Flip-Chip bonded thin silicon chip-on-foil assembly during bending. , 2015, , .		2
6	Finite element analysis of uniaxial bending of ultra-thin silicon dies embedded in flexible foil substrates. , 2015, , .		4
7	Investigations of the fracture strength of thin silicon dies embedded in flexible foil substrates. , 2014, , .		6
8	Conductive layer for charge dissipation during electron-beam exposures. , 2012, , .		2